

Document: MSD-ADIX-SA Version : 2 Date: 2015.06.02

# MACHINE SPECIFICATIONS DOCUMENT

(MSD-ADIX-SA)



(Photo for information only)

**ADIX-SA** 



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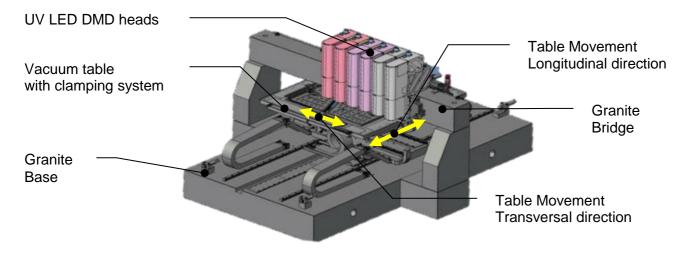
## 1. Equipment Overview

ADIX is an UV LED DMD Direct Imaging solution based on its new ALDS™ technology.

The solution is dedicated for PCB and FPC applications, for high mix low and medium volume production, in inner layer, outer layer, and solder mask processes.

It was designed to reach the best-cost performance.







# 2. Table of Specifications

	Table of Specifications			
APPLICATION	PCB & FPC: HDI • Multilayers • Flex • Rigid-Flex			
Process	Semi-Automatic production of Inner Layers, Outer Layers and Solder Mask			
Exposure area	From 228mm x 254mm (9"x10") up to 610mm x 762mm (24"x30")			
Panel Thickness	0,04 to 6mm			
RESOLUTION (L/S - DAM)	25μm/25μm (1/1 mils) <sup>(1)</sup>			
Light Engine	ALDS™			
Imaging Photo Heads	2 4 6			
Resist Capability	From 10 to 1,000 mJ/cm <sup>2</sup>			
Wavelength	2 UV LED per Head : 365 and 405 nm			
Depth of focus	± 100μm			
Autofocus	Dynamic AF sensor per Head, stroke of ± 2 mm			
RESOLUTION (L/S - DAM)	25μm/25μm (1/1 mils) <sup>(1)</sup>			
Edge Roughness	± 1,5μm			
ALIGNMENT	± 12μm Side to Side Alignment			
ALIGINIVIENT	± 8μm Image to Panel (holes or pads)			
	Side to Side Alignment : 3 cameras			
CCD Cameras	Image to Panel Alignment : 2 cameras			
	Image calibration: 1 camera			
THROUGHPUT	18s with 30mJ/cm <sup>2</sup> resist and 457mm x 610mm (18"x24") image size			
SOFTWARE	ALTIX ADIX SUITE with 19" touch screen			
Data Input	Extended Gerber (RS274X), ODB++ capabilty			
Functionnalities	Scaling, Partitioning, Serialisation			
Languages	All languages available: English, Simplified & Traditional Chinese, Korean, French,			
HIGH YIELD				
Air cleanliness	Hepa filter class 100			
Temperature	$\pm$ 1°C temperature control in Imaging Photo Heads / $\pm$ 2°C temperature control in the unit			
GENERAL UTILITIES				
Power Supply	220/400/480V - 3 Phases - 50/60Hz			
Power Consumption	4kW			
Air Supply	6~7 bars Ÿ 1.5m³/min			
Water Pressure	3 to 5 bars			
Water Flow	23l/min @12°C - 33l/min @14°C			
	4.500			
Machine Weight	4,500kg			

<sup>(1)</sup> Depending on Photoresist, Surface Prepartion and DES process



# 4. Products and Tooling

## 4.1. Product Definition

Basic Material	Single or Double Side PCB (Rigid or Rigid-Flex) Single or Double Side FCCL (Flexible Copper Clad Laminate)		
Product Size	Minimum & Maximum : Refer to Table of Specifications		
	Maximum Width  Minimum Expo Length  Minimum Expo Length		
Product Thicknesses	Minimum & Maximum : Refer to Table of Specifications		
Max. Weight of the product	6kg max.		
Warp and Twist	For panel thickness 0.04 to 0.8mm : 1% of the diagonal For panel thickness 0.8 to 6.0mm : 0.5% of the diagonal		

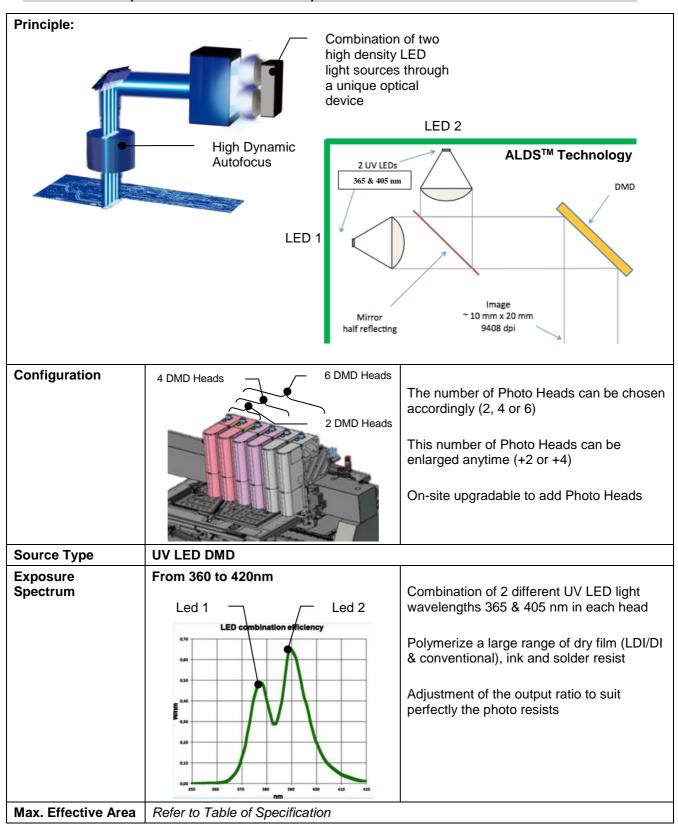
#### 4.2. Photo Resist Definition

Photo Resist Type	Dry Film, Liquid Resist, Solder Mask
Photo Resist Brand / Ref.	Datasheet about the photo resist will be required to confirm the feasibility
Photo Resist Thickness	Datasheet about the photo resist will be required to confirm the feasibility
Photo Resist Energy	Refer to Table of Specifications



### 5. UV Light Source

#### 5.1. ALDS™ (Altix Led DMD Solution)



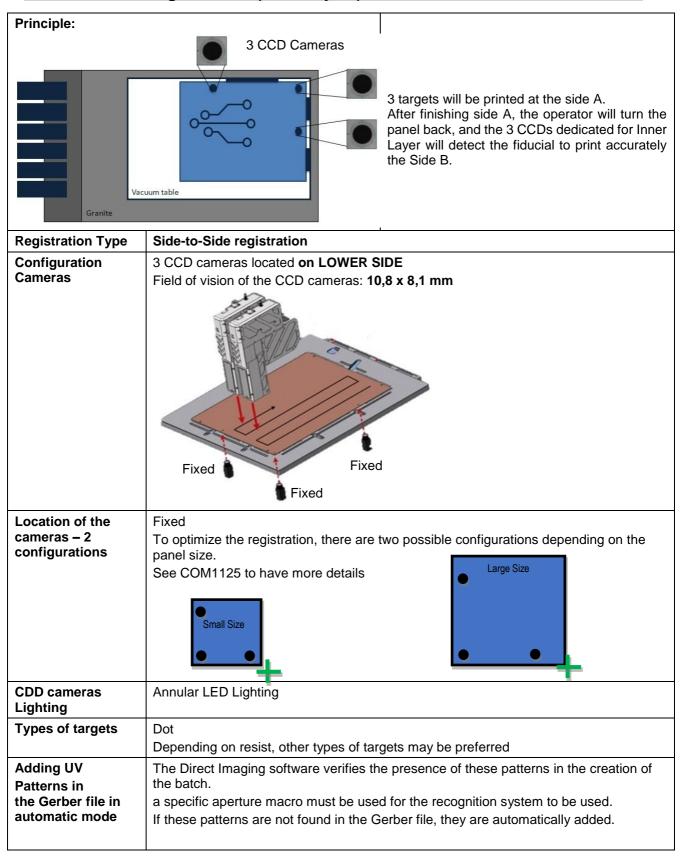


Autofocus	High dynamics autofocus: ± 2,000µm (for each head)	The system comprises one autofocus that enables to compensate the uneven surface of the panels.  Located in each head, there is one sensor, which checks the topography of the panel in real time. The Photo Heads will be able to absorb the thickness variation of ±2mm from the average	
Depth of focus	Depth of Focus (DoF): ±100µm  A sudden variation of the thickness can't be absorbed by the autofocus, but only by the depth-of-focus which is ±100µm  Depth of focus is a lens optics concept that measures the tolerance of placement of the image plane (the film plane in a camera) in relation to the lens. In a camera, depth of focus indicates the tolerance of the film's displacement within the camera, and is therefore sometimes referred to as "lens-to-film tolerance."		
	Depth-of-Focus ±150μm  Sudden variation	Overall topography variation  Dynamic Autofocus ±2mm  Average thickness of the panel	



#### 6. Registration

#### 6.1. Side-to-Side registration (Inner Layers)





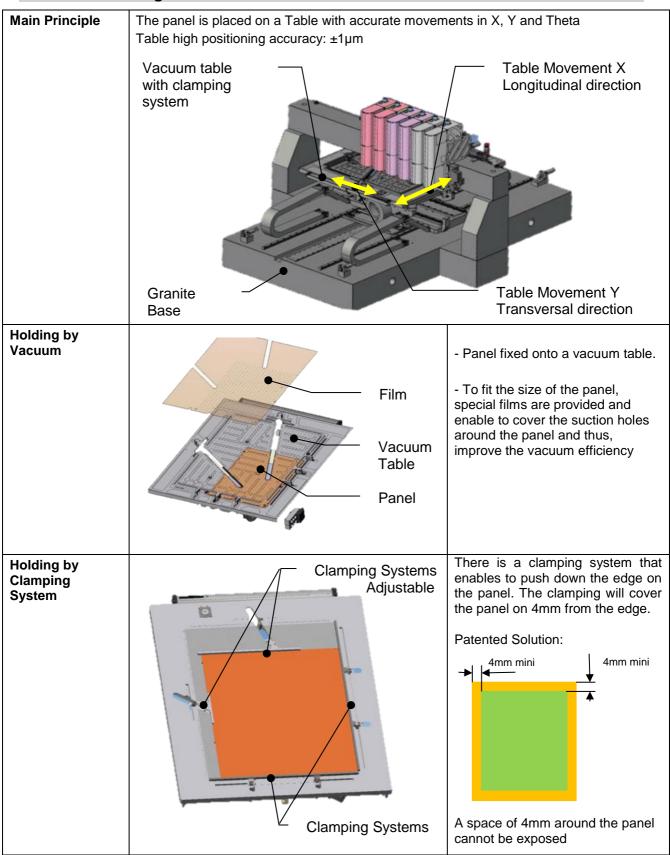
# 6.2. Image to Panel registration (Through holes or Copper pad)

Registration Type  Configuration Cameras  2 CCD cameras (One fixed / One movable) CCD cameras (one fixed / One movable) CCD cameras located on UPPER SIDE Field of vision of the CCD cameras: 10,8 x 8,1 mm  Movable Fixed  Fixed  Indication of the cameras  CDD cameras Lighting  Types of targets on panel  Different target type available: Holes - Microvia holes - Copper pads Nota: Possibility to use other types of targets. The request has to be done to ALTIX R&D for validation, For better possible (request to be done in accordance to ALTIX RAD for validation). For better possible to the panel edges, while respecting the minimum edge space on the edge		
Configuration Cameras  2 CCD cameras (One fixed / One movable) CCD cameras located on UPPER SIDE Field of vision of the CCD cameras: 10,8 x 8,1 mm Movable Fixed  The table is movable and allows to place the targets under the corresponding camera.  Location of the cameras  CDD cameras Lighting  Direct Lighting with dual LED wavelength (red & infrared) Lighting  Types of targets on panel  Different target type available: - Holes - Matrix of holes - Microvia holes - Microvia holes - Copper pads Nota: Possibility to use other types of targets. The request has to be done to ALTIX R&D for validation, during the qualification process of the specifications  Targets location  To optimize the cycle time, it is preferred-to have 4 holes aligned in X and Y; keying it possible (request to be done in accordance to ALTIX R&D for validation). For better positioning of the image, the best is also to have registration holes, as close as		
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Field of vision of the CCD cameras: 10,8 x 8,1 mm  Movable Fixed  The table is movable and allows to place the targets under the corresponding camera.  Location of the cameras  Minimum distance between cameras: 80 mm  CDD cameras  Lighting  Types of targets on panel  Different target type available: - Holes - Matrix of holes - Microvia holes - Copper pads  Nota: Possibility to use other types of targets. The request has to be done to ALTIX R&D for validation, during the qualification process of the specifications  Targets location  To optimize the cycle time, it is preferred-to have 4 holes aligned in X and Y; keying it possible (request to be done in accordance to ALTIX R&D for validation). For better positioning of the image, the best is also to have registration holes, as close as		· ·
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Location of the cameras  CDD cameras Lighting  Direct Lighting with dual LED wavelength (red & infrared)  Types of targets on panel  Different target type available: - Holes - Matrix of holes - Microvia holes - Copper pads  Nota: Possibility to use other types of targets. The request has to be done to ALTIX R&D for validation, during the qualification process of the specifications  Targets location  To optimize the cycle time, it is preferred-to have 4 holes aligned in X and Y; keying in possible (request to be done in accordance to ALTIX R&D for validation). For better positioning of the image, the best is also to have registration holes, as close as		Fixed
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Targets location  To optimize the cycle time, it is preferred-to have 4 holes aligned in X and Y; keying it possible (request to be done in accordance to ALTIX R&D for validation). For better positioning of the image, the best is also to have registration holes, as close as		
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#### 7. Others functions

#### 7.1. Panel handling





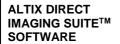
#### 7.2. Cleanliness

Basic Frame construction	Stainless Steel	Mile Private Las.  Jacob Company of the All
Hepa Filter or Clean Kit		
Dry Clean Air Supply (CDA)		

#### 7.3. Machine Environment Control

Ambient Temperature	Built-in temperature control: ±0.5°C		

#### 7.4. Machine Environment Control





Friendly and intuitive graphical user interface Smooth connectivity to CAM ensures fast and easy setup

Recognize a wide array of different target types RIP different CAM files



The ADIX system consists of a data-processing unit that receives and rasterizes Gerber files from CAM station file inside the DI machine and queue them as soon as the operator validate a production batch. A RIP station can be installed for the convenience and comfort of the operator and production department. It will also be useful to use the ODB++ to Gerber conversion software ALTIX can provide upon request. CAM Station Data processing Unit directly **Human Interface** Only one Large touch screen 19" to dialog between operator and machine All languages available (English, Simplified & Traditional Chinese, Korean, French, ...) Type of Data **Extended Gerber** Input ODB++ **Partitioning** Partitions can be decomposed from Indivual Zones (example for 2 partitions) 1 to 8 Zone 1 Target located either as Individual Zones Extended Zones Shared Zones Zone 2 **Extended Zones** (example for 2 partitions) Zone 1 Zone 2 Shared Zones (example for 2 partitions) one Zone 2



Scaling Mode	<ul> <li>Fixed scaling set on batch data</li> <li>SFx and SFy are linear</li> <li>SFx and SFy can be either equal or different</li> </ul>		
	(dedicated mainly to Inner Layers)  Orthogonal XY as measured  SFx and SFy are calculated by  Vision software on each panel and scaling applied is equal to		
	Mean (SFx, SF Orthogonal X&Y as me SFx and SFy are calcula Vision software on each SFx & SFy can be differe	asured ted by panel	
	Dynamic or Nearest Neighbour Distorsions are calculated so that: Item «A» on the figure will be offset according to the distance to the nearest neighbouring fiducials and the corresponding error vectors. In this case, the error vector (dx1,dy1) will be weighted most compared to the other surrounding error vectors. Correspondingly, item «B» will be offset according to the distance from the error vector (dx4,dy4) more than the other surrounding error vectors.		Observed auxiliary fiducial coordinates  Artwork within a zone on a panel  Object inside artwork to be offset by nearest neighbour algorithm
Serialisation	Scaling Parameters	SFx: 1.0000° SFy: 1.00008	
	Image Serial Number	ID:_009	
	Batch Serial Number		
	Date	16/02/2014 16:05	
SPC <sup>2</sup> Module		duction parame	the ALTIX DIRECT IMAGING SUITE™ SOFTWARE. ters and performances of the unit. is
Telemaintenance			LTIX's Engineers can troubleshoot, diagnose and omatech and Customer maintenance staff

# 8. Performances

# 8.1. Alignment Precision

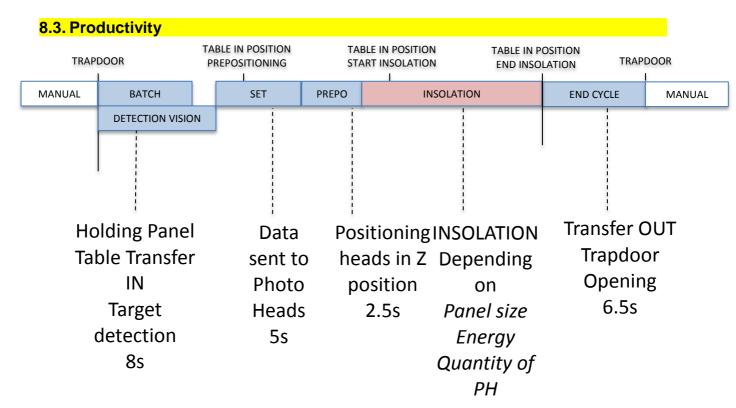
Alignment	Refer to Table of Specification
Accuracy	



## 8.2. Resolution

Line / Space	Refer to Table of Specification (depending on Photo Resist and process capability of the customer)	Main other conditions advised to achieve fine line resolution:  - Dry film adapted to resolution down to the resolution required (Type, Quality, Thickness)  - Surface preparation adapted to resolution required  - Lamination process adapted to resolution required  - Development process adapted to resolution required (Use current developing equipment and parameter, if adapted to resolution required)
Edge Roughness	Refer to Table of Specification	





Panel size: 18" x 24" (457mm x 610mm)

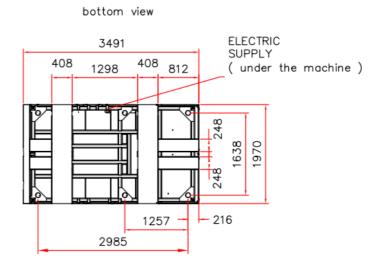
Energy	10mJ/c m²	20mJ/cm <sup>2</sup>	30mJ/cm <sup>2</sup>	40mJ/cm <sup>2</sup>	50mJ/cm <sup>2</sup>	70mJ/cm <sup>2</sup>	100mJ/cm <sup>2</sup>
2 Photo Heads	61.8s	68.0s	83.1s	85.8s	92.3s	114.3s	146.8s
пеаиз	58 side/h	53 side/h	43 side/h	42 side/h	39 side/h	32 side/h	25 side/h
4 Photo	48.4s	52.2s	61.6s	63.2s	67.2s	80.7s	100.8s
Heads	74 side/h	69 side/h	58 side/h	57 side/h	54 side/h	45 side/h	36 side/h
6 Photo	40.0s	42.4s	48.2s	49.3s	51.8s	60.2s	72.7s
Heads	90 side/h	85 side/h	75 side/h	73 side/h	70 side/h	60 side/h	50 side/h

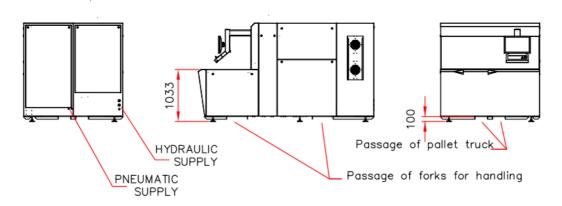
# 9. Options

Pneumatic Air filtration	Optional Submicronic filter
Water filter on Water Network	Optional 1 or 2 filters



# 10. Layout (Altix ref. COM 1101-6)





## 11. Utilities

External Dimensions Length x Width x Height	Refer to Table of Specification
Machine weight	Refer to Table of Specification
Electrical supply	220/400/480 V - 50Hz - 3 phases
	Tolerance on Voltage: ± 6%
	Refer to Table of Specification
Pneumatic supply	Pressure: Refer to Table of Specification
	Air flow: Refer to Table of Specification
Water supply	Pressure: Refer to Table of Specification
	Difference of pressure (input pressure – Output pressure) > 1 bars
	Temperature: 12 to 14°C
	Water flow: Refer to Table of Specification
	To avoid corrosion pH must be around 7



#### 12. Installation Environment

Comply with conditions given below for achieving and maintaining the optimal performance of the exposure system.

Location	Clean Room
Installation Conditions	Ambient Temperature: 20±2°C
	Relative Humidity: 50% RH ±5%
Room illumination	Inactinic yellow light
Clean room	Recommended cleanliness
	Class 10,000
	(10,000 or less particles of size 0.5μm per cube foot)

## 13. Customization